

REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	ECO 2136064: Initial Release	11/09/13	HPC
B	ECO 2138298: Change J2 part number	12/05/13	GW
C	ECO 2139941: Up-date file names, Title block	02/14/14	HPC
D	ECO 2140579: Up-date top & bottom assembly diagrams	03/12/14	HPC
E	ECO 214080: Up-date ESD , PCB, & BOM drawing numbers; top & bottom assembly diagrams	03/13/14	HPC

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		DWN/CHK Paul Cleveland	DATE 02/14/2014	CCA, NIRscan Detector Board		
		SYS ENGR				
	0314CP	MANU				
NHA	USED ON	QA		SIZE A	DRAWING NO 2513460	REV E
APPLICATION		APVD		SCALE NONE	SHEET 1 OF 5	

1. Scope

The purpose of this document is to establish the assembly requirements for the Detector Amplifier Board.

2. Related Documents

Texas Instruments Documents

Dwg. Number	Document Name
2513458	2513458d_NIRscan_Detector_Board_ESD
2513459	2513459c_NIRscan_Detector_Board_PCB

3. Notes

1. This PCB contains devices which are electrostatic discharge sensitive.
2. Mark the appropriate Manufacturing Serial Number (MSN) on the top of the PCB. Method and placement location optional.
3. Mark assembly number, assembly dash number and revision letter of CCA on the top of the PCB. Method and placement location optional.
4. Workmanship to be in accordance with ANSI/IPC-A-610B Class 2 and ANSI/J-STD-001A Class 2.
5. Equivalent or better part may be substituted.
6. Solder times and temperatures to be in conformance with PWB UL component recognition limits established for the particular board. The solder profile must also comply with the limits of all components on the PCB.
7. Components and processes should be lead-free and ROHS compliant.

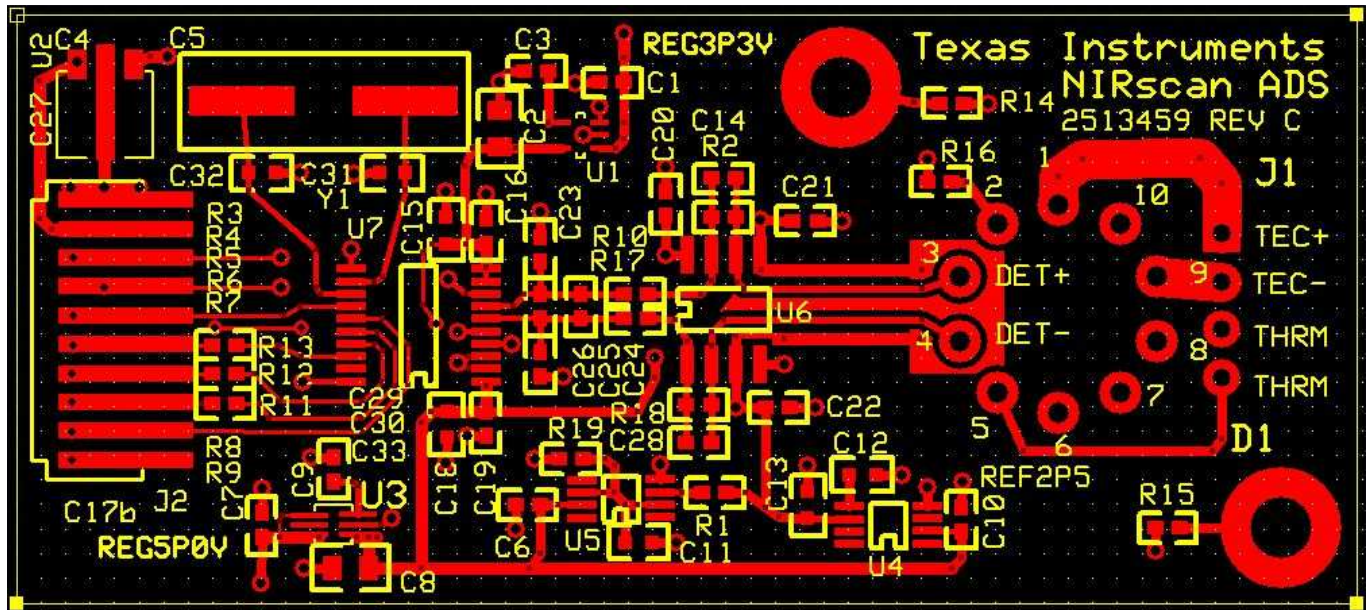
4. Bill of Material & Cross Reference List

Assembly bill of material and cross reference list are provided in attached spread sheet.

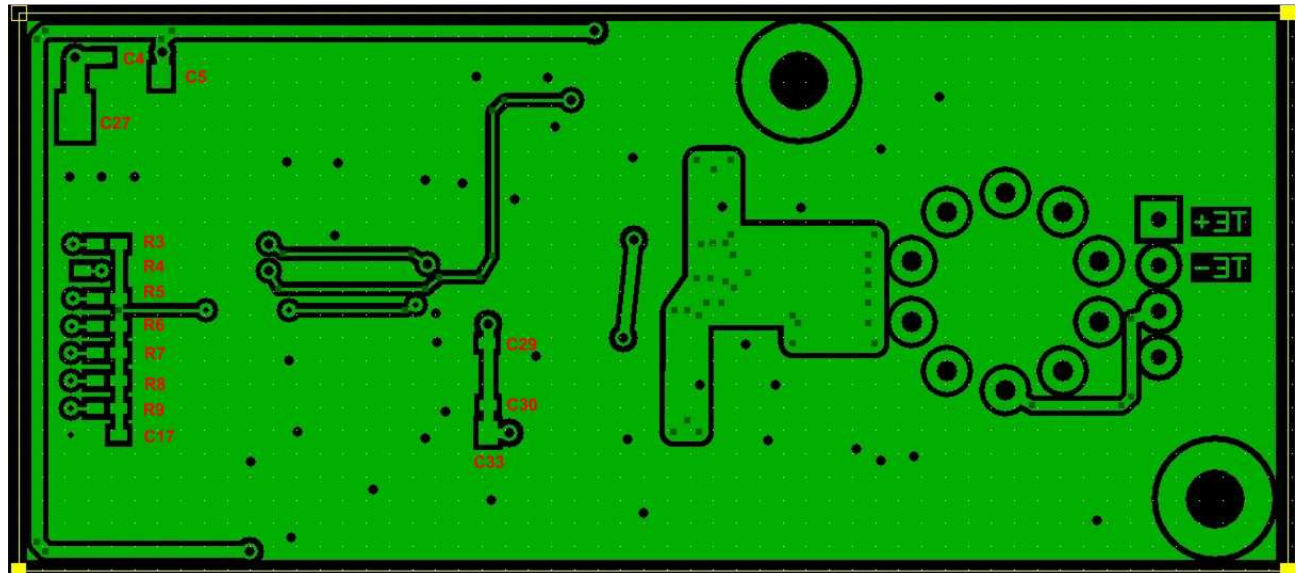
Assembly Dash	Description	Material & Cross Reference List Spread Sheet
-1	Detector Amplifier Board	2513461c_NIRscan_Detector_Board_BOM

5. Assembly Diagrams

Detector Amplifier Top



Detector Amplifier Bottom



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